MOSFET - Power for 1-Cell **Lithium-ion Battery Protection**



This power MOSFET features a low on-state resistance. This device is suitable for applications such as power switches of portable machines. Best suited for 1-cell lithium-ion battery applications.

Features

- 2.5 V drive
- Common–Drain type
- ESD Diode-Protected Gate
- Pb-Free, Halogen Free and RoHS Compliance

Typical Applications

• 1-Cell Lithium-ion Battery Charging and Discharging Switch

SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS at $T_A = 25^{\circ}C$

Parameter	Symbol	Value	Unit
Source to Source Voltage	V _{SSS}	12	V
Gate to Source Voltage	V_{GSS}	±8	V
Source Current (DC)	I _S	40	Α
Source Current (Pulse) PW ≤ 10 μS, Duty Cycle ≤ 1%	I _{SP}	140	Α
Total Dissipation (Note 1)	P _T	3.3	W
Junction Temperature	TJ	150	°C
Storage Temperature	T _{stg}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction to Ambient (Note 1)	$R_{ heta JA}$	37	°C/W

1. Surface mounted on ceramic substrate (5000 $\text{mm}^2 \times 0.8 \text{ mm}$)

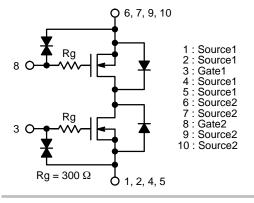


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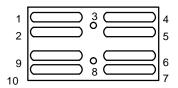
www.onsemi.com

V _{SSS}	R _{SS(ON)} MAX	I _S MAX
12 V	1.8 mΩ @ 4.5 V	40 A
	1.9 mΩ @ 3.8 V	
	2.6 mΩ @ 3.1 V	
	4.2 mΩ @ 2.5 V	

ELECTRICAL CONNECTION N-Channel



PIN ASSIGNMENT



MARKING DIAGRAM





WLCSP10 3.54x1.77x0.140 CASE 567XB

PB = Specific Device Code = Assembly Location

= Year

W = Work Week ZZ = Assembly Lot

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 2 of this data sheet.

ELECTRICAL CHARACTERISTICS at T_A = 25°C

				Value			
Parameter	Symbol	Condition	ıs	Min	Тур	Max	Unit
Source to Source Breakdown Voltage	V _{(BR)SSS}	I _S = 1 mA, V _{GS} = 0 V	Test Circuit 1	12	-	-	V
Zero Gate Voltage Source Current	I _{SSS}	V _{SS} = 10 V, V _{GS} = 0 V	Test Circuit 1	-	-	1	μΑ
Gate to Source Leakage Current	I _{GSS}	$V_{GS} = \pm 8 \text{ V}, V_{SS} = 0 \text{ V}$	Test Circuit 2	-	_	±1	μΑ
Gate Threshold Voltage	V _{GS} (th)	$V_{SS} = 6 \text{ V}, I_{S} = 1 \text{ mA}$	Test Circuit 3	0.4	-	1.3	V
Static Source to Source On–State Resistance	R _{SS} (on)	$I_S = 5 \text{ A}, V_{GS} = 4.5 \text{ V}$	Test Circuit 4	0.8	1.25	1.8	mΩ
		I _S = 5 A, V _{GS} = 3.8 V	Test Circuit 4	0.85	1.35	1.9	mΩ
		I _S = 5 A, V _{GS} = 3.1 V	Test Circuit 4	1.0	1.7	2.6	mΩ
		I _S = 5 A, V _{GS} = 2.5 V	Test Circuit 4	1.2	2.1	4.2	mΩ
Turn-ON Delay Time	t _d (on)	V _{SS} = 6 V, V _{GS} = 3.8 V, I _S = 5 A,		-	25	_	μS
Rise Time	t _r	R_G = 10 kΩ Test Circuit 5	R_G = 10 kΩ Test Circuit 5		100	-	μS
Turn-OFF Delay Time	t _d (off)			-	165	-	μS
Fall Time	t _f			-	148	-	μS
Total Gate Charge	Qg	V_{SS} = 6 V, V_{GS} = 3.8 V, I_{S} Test Circuit 6	= 5 A	-	62	-	nC
Forward Source to Source Voltage	V _{F(S-S)}	I _S = 3 A, V _{GS} = 0 V	Test Circuit 7	-	0.75	1.2	V

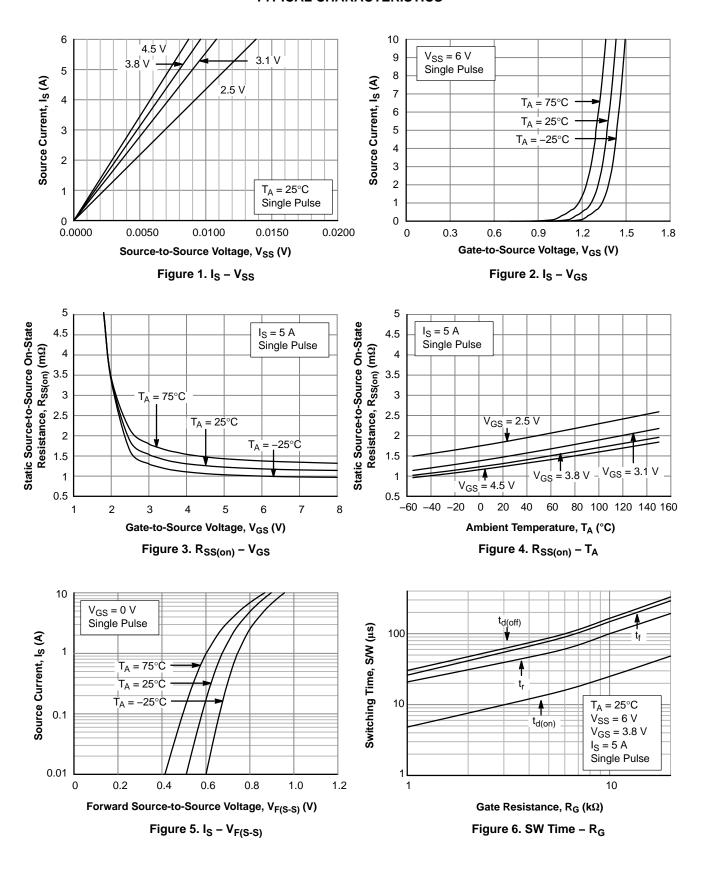
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Device	Marking	Package	Shipping (Qty / Packing) [†]
EFC2K103NUZTDG	РВ	WLCSP10, 3.54 × 1.77 × 0.140 (Pb–Free / Halogen Free)	5,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS (Continued)

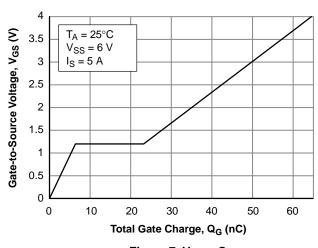


Figure 7. V_{GS} – Q_{G}

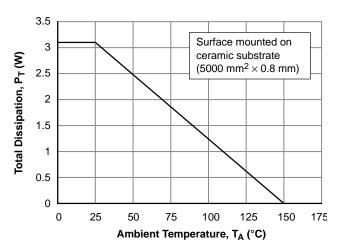


Figure 8. P_T – T_A

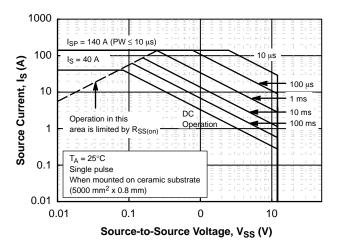


Figure 9. Safe Operating Area

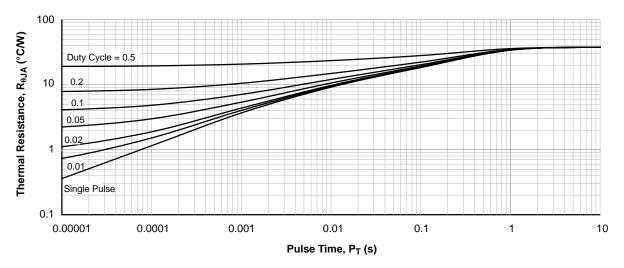


Figure 10. Thermal Response

TEST CIRCUITS ARE EXAMPLES OF MEASURING FET1 SIDE

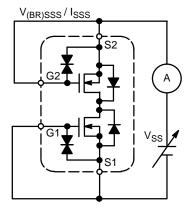
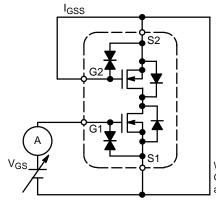


Figure 11. Test Circuit



When FET1 is measured, Gate and Source of FET2 are short–circuited.

Figure 12. Test Circuit

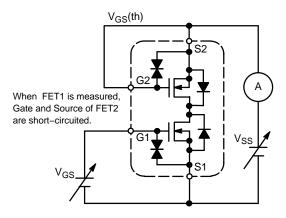


Figure 13. Test Circuit 3

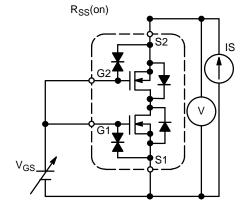


Figure 14. Test Circuit

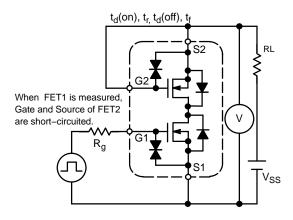


Figure 15. Test Circuit 5

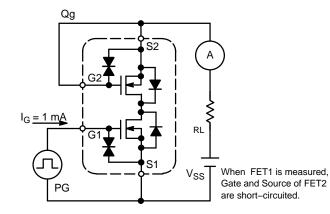


Figure 16. Test Circuit

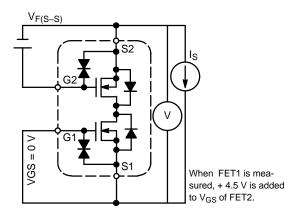
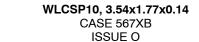


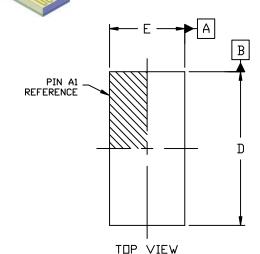
Figure 17. Test Circuit

NOTE: When FET2 is measured, the position of FET1 and FET2 is switched.

NOTE: Since the EFC2K103NUZ is a MOSFET product, please avoid using this device in the vicinity of highly charged objects. Please contact sales for use except the designated application.



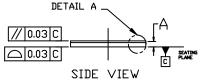
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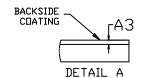


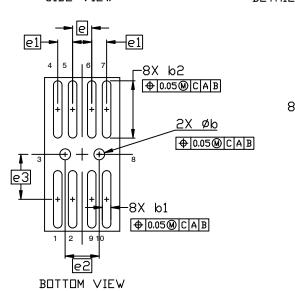
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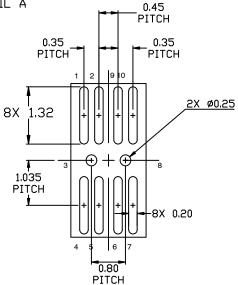
- I. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS

	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α	0.11	0.14	0.17	
A3		0.04 REF		
b	0.22	0.25 0.28		
b1	0.17	0.20	0.23	
b2	1.29	1.32	1.35	
D	3.51	3.54	3.57	
Ε	1.74	1.77	1.80	
е	0.45 BSC			
e1	0.35 BSC			
e2	0.80 B2C			
e3	1.035 BSC			









RECOMMENDED MOUNTING FOOTPRINT

GENERIC
MARKING DIAGRAM*

XXXXX= AYWZZ= XXXX = Specific Device Code

A = Assembly Location
Y = Year

W = Work WeekZZ = Assembly Lot Code

= Pb-Free Package(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	WLCSP10, 3.54x1.77x0.14		PAGE 1 OF 1	

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